

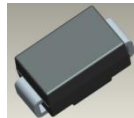
Features

- Very Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automated Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 70A Peak
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

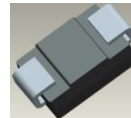
Mechanical Data

- Case: SMA/SMB
- Case Material: Molded Plastic; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 ③
- Polarity: Cathode Band or Cathode Notch
- Weight: SMA 0.064 grams (Approximate)
SMB 0.093 grams (Approximate)

SMA/SMB



Top View



Bottom View

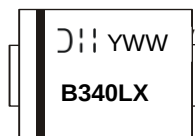
Ordering Information (Note 4)

Part Number	Case	Packaging
B340LA-13-F	SMA	5,000/Tape & Reel
B340LB-13-F	SMB	3,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

SMA/SMB



B340LA = Product Type Marking Code, ex: B340LA (SMA Package)
 B340LB = Product Type Marking Code, ex: B340LB (SMB Package)
 ☽|| = Manufacturer's Code Marking
 YWW = Date Code Marking
 Y = Last Digit of Year (ex: 6 for 2016)
 WW = Week Code (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	40	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_R		
Average Rectified Output Current (Note 5) $T_T = +90^\circ\text{C}$	I_O	3.0	A
Non-Repetitive Peak Forward Surge Current, Single Sine-Wave Superimposed on Rated Load, 60Hz	I_{FSM}	70	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Conditions
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	40	—	—	V	I _R = 2.0mA
Forward Voltage Drop	V _F	— —	0.310 —	0.350 0.450	V	I _F = 1.0A I _F = 3.0A
Leakage Current (Note 6)	I _R	—	—	150	μA	V _R = 15V
			—	1.0	mA	V _R = 20V
			—	2.0		V _R = 40V
Total Capacitance	C _T	—	180	—	pF	f = 1MHz, V _R = 4.0VDC
Thermal Resistance, Junction to Terminal	R _{θJT}	—	35	—	°C/W	—

Notes: 5. Device mounted on FR-4 substrate, 0.4"×0.5", 2oz, single-sided, PC boards with 0.2"×0.25" copper pad.
 6. Short duration pulse test used to minimize self-heating effect.

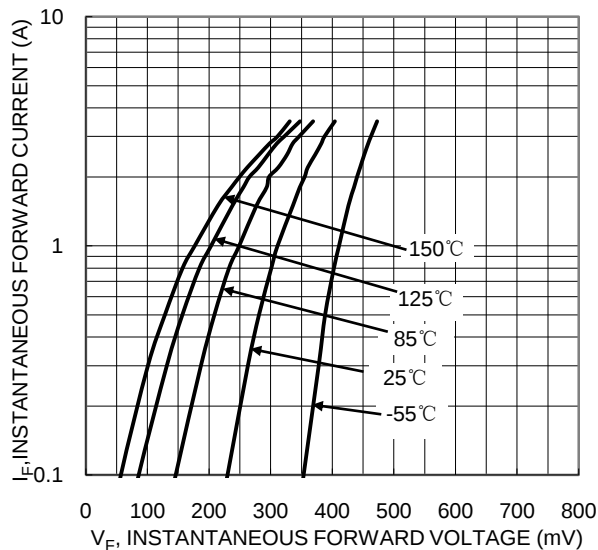


Figure 1. Typical Forward Characteristics

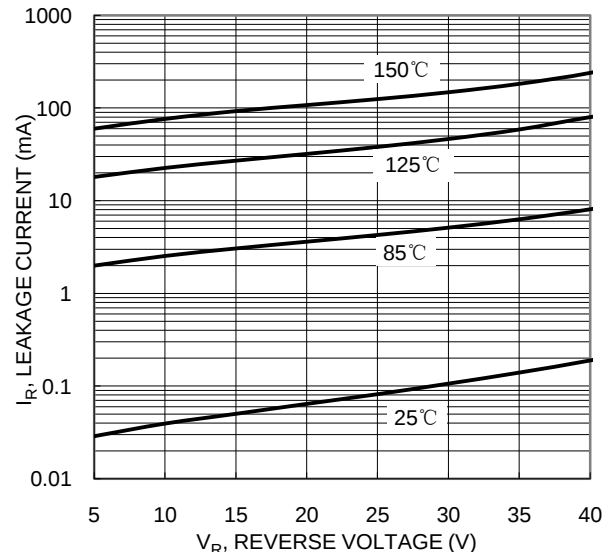
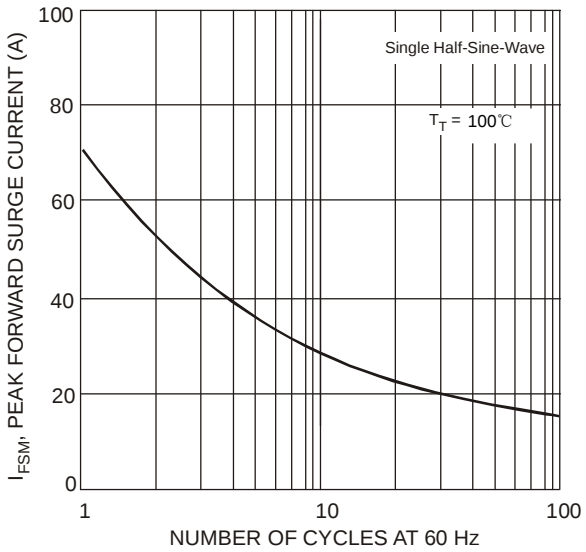
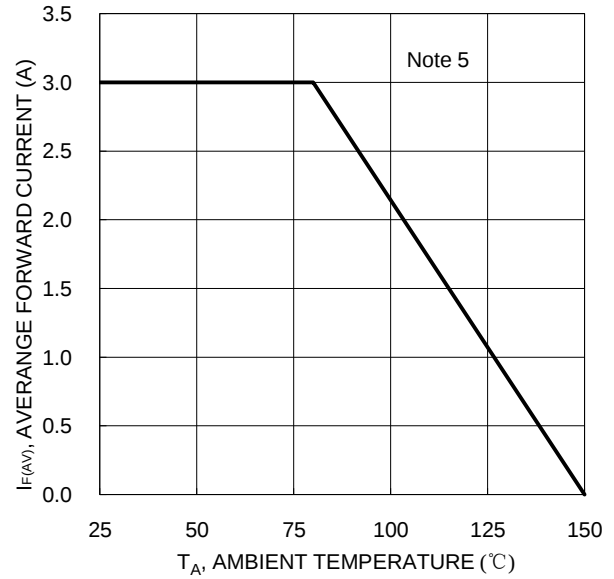
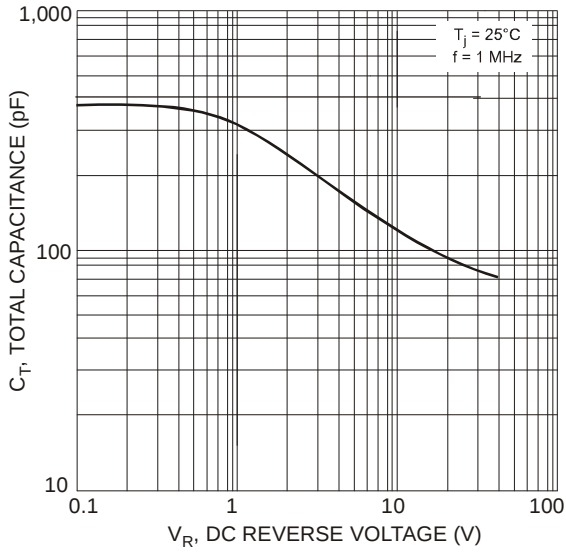


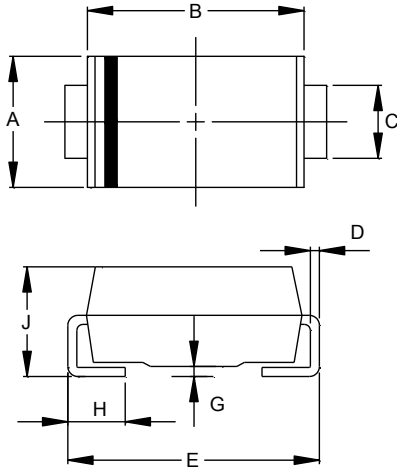
Fig.2 Typical Reverse Characteristics



Package Outline Dimensions

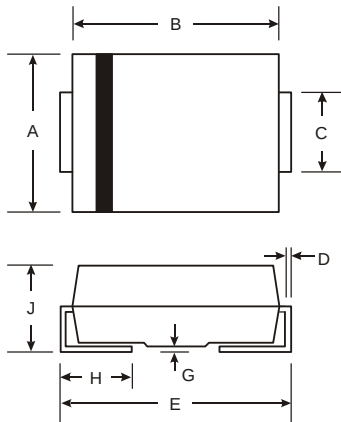
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

1) Package Type:SMA



SMA		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	1.96	2.40
All Dimensions in mm		

2) Package Type:SMB

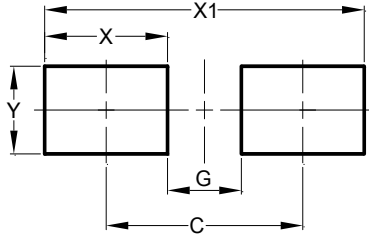


SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

Suggested Pad Layout

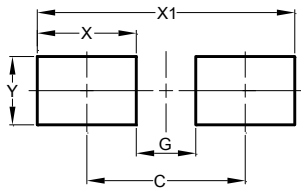
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

1) Package Type:SMA



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

2) Package Type:SMB



Dimensions	Value (in mm)
C	4.30
G	1.80
X	2.50
X1	6.80
Y	2.30

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